L Number	Hits	Search Text	DB	Time stamp
1	2552477	semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 19:44
2	8128983	1with (through hope via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 19:43
3	428874	(semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 19:44
4	159597	(wiring) with (substrate board carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 19:44
5	14968	((semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via)) same ((wiring) with (substrate board carrier))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 19:44
6	703	(flipchip (flip adj chip)) same (((semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via)) same ((wiring) with (substrate board carrier)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 19:46
7	417	((flipchip (flip adj chip)) same (((semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via)) same ((wiring) with (substrate board carrier)))) and (package packaging packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 19:46

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